

M Z Abdullah

List of Publications by Year in descending order

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287
all docs

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docs citations

287
times ranked

3109
citing authors

#	ARTICLE	IF	CITATIONS
1	Effects of Blade Number on the Centrifugal Pump Performance: A Review. Arabian Journal for Science and Engineering, 2022, 47, 7945-7961.	3.0	9
2	Overview of the Important Factors Influencing the Performance of Eco-Friendly Brake Pads. Polymers, 2022, 14, 1180.	4.5	20
3	Heat transfer analysis on wafer annealing process in semiconductor multi-wafer furnace using CFD simulation. Journal of Mechanical Science and Technology, 2022, 36, 3143-3151.	1.5	2
4	Prediction of the void formation in no-flow underfill process using machine learning-based algorithm. Microelectronics Reliability, 2022, 135, 114586.	1.7	1
5	Numerical study on the influence of nozzle spray shape on spray characteristics using diesel and biofuel blends. Biofuels, 2021, 12, 1109-1121.	2.4	8
6	Heat transfer and deformation analysis of flexible printed circuit board under thermal and flow effects. Circuit World, 2021, 47, 213-221.	0.9	1
7	Mechanical reliability of self-aligned chip assembly after reflow soldering process. Soldering and Surface Mount Technology, 2021, 33, 9-17.	1.5	3
8	Design and Fabrication of a Dual Rotor-Embedded Wing Vertical Take-Off and Landing Unmanned Aerial Vehicle. Unmanned Systems, 2021, 09, 45-63.	3.6	7
9	Selected water thermal properties from molecular dynamics for engineering purposes. Journal of Molecular Liquids, 2021, 324, 114703.	4.9	15
10	Effect of volume concentration and nanofluid temperature on the thermal conductivity of mono and hybrid Al ₂ O ₃ -TiO ₂ nanofluid. AIP Conference Proceedings, 2021, , .	0.4	7
11	Study of Different Dispensing Patterns of No-Flow Underfill Using Numerical and Experimental Methods. Journal of Electronic Packaging, Transactions of the ASME, 2021, 143, .	1.8	3
12	Correlating scalants characteristic and air bubbling rate in submerged vacuum membrane distillation: A fouling control strategy. Journal of Membrane Science, 2021, 621, 118991.	8.2	11
13	Investigations of Infrared Desktop Reflow Oven with FPCB Substrate during Reflow Soldering Process. Metals, 2021, 11, 1155.	2.3	12
14	Performance, combustion characteristics and economics analysis of a combined thermoelectric and thermophotovoltaic power system. Applied Thermal Engineering, 2021, 193, 117051.	6.0	5
15	Enhancement in Cathodic Redox Reactions of Single-Chambered Microbial Fuel Cells with Castor Oil-Emitted Powder as Cathode Material. Materials, 2021, 14, 4454.	2.9	6
16	Recent Advances on Thermally Conductive Adhesive in Electronic Packaging: A Review. Polymers, 2021, 13, 3337.	4.5	22
17	Die attachment, wire bonding, and encapsulation process in LED packaging: A review. Sensors and Actuators A: Physical, 2021, 329, 112817.	4.1	37
18	Optimization of flexible printed circuit board's cooling with air flow and thermal effects using response surface methodology. Microelectronics International, 2021, 38, 182-205.	0.6	3

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19	Double-Layer Micro Porous Media Burner from Lean to Rich Fuel Mixture: Analysis of Entropy Generation and Exergy Efficiency. <i>Entropy</i> , 2021, 23, 1663.	2.2	2
20	Design Optimization of Solid Rocket Propulsion: A Survey of Recent Advancements. <i>Journal of Spacecraft and Rockets</i> , 2020, 57, 3-11.	1.9	25
21	Effect of pin inclination angle on flow and heat transfer characteristics for a row of pins in a flow channel. <i>International Communications in Heat and Mass Transfer</i> , 2020, 110, 104396.	5.6	6
22	Effect of adhesive force on underfill process based on lattice Boltzmann method. <i>Microelectronics International</i> , 2020, 37, 54-63.	0.6	3
23	Experimental analysis on combustion characteristics of single layer porous media for various burner sizes. <i>IOP Conference Series: Materials Science and Engineering</i> , 2020, 852, 012085.	0.6	0
24	Viscosity of Mono vs Hybrid Nanofluids: Measurement and Comparison. <i>IOP Conference Series: Materials Science and Engineering</i> , 2020, 852, 012086.	0.6	1
25	Lead-free solder SAC 305 Volume Reduction and Cold Slump after Stencil Printing Process. <i>IOP Conference Series: Materials Science and Engineering</i> , 2020, 852, 012084.	0.6	0
26	Entropy Generation and Exergy Analysis of Premixed Fuel-Air Combustion in Micro Porous Media Burner. <i>Entropy</i> , 2020, 22, 1104.	2.2	4
27	Thermophysical properties of Al ₂ O ₃ -CuO hybrid nanofluid at different nanoparticle mixture ratio: An experimental approach. <i>Journal of Molecular Liquids</i> , 2020, 313, 113458.	4.9	50
28	Three-dimensional CFD simulation of the stencil printing performance of solder paste. <i>International Journal of Advanced Manufacturing Technology</i> , 2020, 108, 3351-3359.	3.0	7
29	Metal oxide nanofluids in electronic cooling: a review. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 4381-4398.	2.2	43
30	Performance of Functionalized MWCNTs-Water Nanofluids for Heat Transfer Applications. <i>Arabian Journal for Science and Engineering</i> , 2020, 45, 5603-5614.	3.0	4
31	Study on the Addition of Nanoparticles in the Lead-free Solder During Reflow Soldering via Numerical Simulation - A Review. <i>CFD Letters</i> , 2020, 12, 111-119.	0.8	4
32	Effect of Contact Angle on Meniscus Evolution and Contact Line Jump of Underfill Fluid Flow in Flip-Chip Encapsulation. <i>CFD Letters</i> , 2020, 12, 28-38.	0.8	2
33	Symmetrical Unit-Cell Numerical Approach for Flip-Chip Underfill Flow Simulation. <i>CFD Letters</i> , 2020, 12, 55-63.	0.8	5
34	CAD-Based 3D Grain Burnback Analysis for Solid Rocket Motors. <i>Lecture Notes in Mechanical Engineering</i> , 2020, , 341-348.	0.4	0
35	Thermal Impact of Heat Spreader Co-Planarity to Electronic Packaging. <i>Journal of Advanced Research in Fluid Mechanics and Thermal Sciences</i> , 2020, 71, 1-9.	0.6	0
36	Heat Transfer Performance of a Synthetic Jet at Various Driving Frequencies and Diaphragm Amplitude. <i>Arabian Journal for Science and Engineering</i> , 2019, 44, 1043-1055.	3.0	6

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37	Development of foam porous media to undergo surface and submerged flame during premixed combustion. IOP Conference Series: Materials Science and Engineering, 2019, 505, 012123.	0.6	2
38	A novel analytical filling time chart for design optimization of flip-chip underfill encapsulation process. International Journal of Advanced Manufacturing Technology, 2019, 105, 3521-3530.	3.0	6
39	Numerical simulation of thermal fluid-structure interaction on flexible PCB in reflow soldering atmosphere. AIP Conference Proceedings, 2019, , .	0.4	0
40	Enhancement of nanofluid heat transfer in a mini-tube using SiO ₂ nanoparticles. Advances in Materials and Processing Technologies, 2019, 5, 607-616.	1.4	4
41	Thermal Analysis of a Cylindrical Sintered Wick Heat Pipe. Advanced Structured Materials, 2019, , 307-319.	0.5	0
42	Heat Transfer and Entropy Generation Abilities of MWCNTs/GNPs Hybrid Nanofluids in Microtubes. Entropy, 2019, 21, 480.	2.2	57
43	Experimental Investigation of Water-Cooled Heat Pipes in the Thermal Management of Lithium-Ion EV Batteries. Arabian Journal for Science and Engineering, 2019, 44, 7541-7552.	3.0	18
44	Comparative Study of Pressurized and Capillary Underfill Flow Using Lattice Boltzmann Method. Arabian Journal for Science and Engineering, 2019, 44, 7627-7652.	3.0	8
45	Stencil printing process performance on various aperture size and optimization for lead-free solder paste. International Journal of Advanced Manufacturing Technology, 2019, 102, 3369-3379.	3.0	15
46	Optimization of 3D IC stacking chip on molded encapsulation process: a response surface methodology approach. International Journal of Advanced Manufacturing Technology, 2019, 103, 1139-1153.	3.0	7
47	Numerical Analysis of Nozzle Flow and Spray Characteristics from Different Nozzles Using Diesel and Biofuel Blends. Energies, 2019, 12, 281.	3.1	28
48	Effect of Ultra-low Vegetable Oil Droplets on Microporous Media Burner Under Surface and Submerged Flames. Arabian Journal for Science and Engineering, 2019, 44, 5921-5935.	3.0	1
49	Influence of reaction layer thickness on surface/submerged flame during porous media combustion of micro burner. IOP Conference Series: Materials Science and Engineering, 2019, 508, 012072.	0.6	1
50	Finite Volume Method Study on Contact Line Jump Phenomena and Dynamic Contact Angle of Underfill Flow in Flip-Chip of Various Bump Pitches. IOP Conference Series: Materials Science and Engineering, 2019, 530, 012012.	0.6	5
51	Molecular dynamics simulation of the nano- reinforced lead-free solder at different reflow soldering process temperature. IOP Conference Series: Materials Science and Engineering, 2019, 701, 012014.	0.6	2
52	Filling efficiency of flip-chip underfill encapsulation process. Soldering and Surface Mount Technology, 2019, 32, 10-18.	1.5	13
53	Temperature Prediction on Flexible Printed Circuit Board in Reflow Oven Soldering for Motherboard Application. IOP Conference Series: Materials Science and Engineering, 2019, 530, 012019.	0.6	3
54	Nanofluid-filled heat pipes in managing the temperature of EV lithium-ion batteries. Journal of Physics: Conference Series, 2019, 1349, 012123.	0.4	12

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55	Numerical Study of Heat Transfer Enhancement Using Al ₂ O ₃ -Graphene/Water Hybrid Nanofluid Flow in Mini Tubes. Iranian Journal of Science and Technology, Transaction A: Science, 2019, 43, 1989-2000.	1.5	25
56	Effect of filling level and fillet profile on pin-through-hole solder joint. International Journal of Advanced Manufacturing Technology, 2019, 102, 1467-1485.	3.0	3
57	Study of velocity profiles of orbal biological system (OBS) using computational fluid dynamics (CFD). Journal of Computational Methods in Sciences and Engineering, 2019, 19, 447-454.	0.2	1
58	Study on convective heat transfer and pressure drop of MWCNTs/water nanofluid in mini-tube. Journal of Thermal Analysis and Calorimetry, 2019, 135, 123-132.	3.6	17
59	A Brief Survey of Preparation and Heat Transfer Enhancement of Hybrid Nanofluids. Strojinski Vestnik/Journal of Mechanical Engineering, 2019, , 441-453.	1.1	31
60	Flow Analysis Inside Coated Porous Media. Advanced Structured Materials, 2019, , 153-160.	0.5	1
61	NUMERICAL AND EXPERIMENTAL INVESTIGATIONS OF SPEAKER-DRIVEN SYNTHETIC JET ACTUATOR FOR ELECTRONICS COOLING APPLICATIONS. Heat Transfer Research, 2019, 50, 1369-1381.	1.6	3
62	Effect of Different S AC Based Nanoparticles Types on the Reflow Soldering Process of Miniaturized Component using Discrete Phase Model Simulation. Journal of Applied Fluid Mechanics, 2019, 12, 1683-1696.	0.2	3
63	Comparative study on porous media combustion characteristics using different discrete materials. MATEC Web of Conferences, 2018, 153, 01007.	0.2	4
64	Effect of scale size, orientation type and dispensing method on void formation in the CUF encapsulation of BGA. Sadhana - Academy Proceedings in Engineering Sciences, 2018, 43, 1.	1.3	10
65	Investigation on nano-reinforced solder paste after reflow soldering part 1: Effects of nano-reinforced solder paste on melting, hardness, spreading rate, and wetting quality. Microelectronics Reliability, 2018, 84, 230-237.	1.7	9
66	Effect of solder bump shapes on underfill flow in flip-chip encapsulation using analytical, numerical and PIV experimental approaches. Microelectronics Reliability, 2018, 81, 41-63.	1.7	26
67	Heat Transfer in a Loop Heat Pipe using Diamond-H ₂ O Nanofluid. Heat Transfer Engineering, 2018, 39, 1117-1131.	1.9	12
68	Investigation of micro burner performance during porous media combustion for surface and submerged flames. IOP Conference Series: Materials Science and Engineering, 2018, 370, 012049.	0.6	2
69	Flow Behavior Analysis of Emc in Molded Underfill (Muf) Encapsulation for Multi Flip-Chip Package. Journal of Physics: Conference Series, 2018, 1082, 012015.	0.4	2
70	Visualization of Underfill Flow in Ball Grid Array (BGA) using Particle Image Velocimetry (PIV). IOP Conference Series: Materials Science and Engineering, 2018, 370, 012064.	0.6	1
71	Effect of the gap height of radial gate on the volumetric flow rate in dam. IOP Conference Series: Materials Science and Engineering, 2018, 370, 012062.	0.6	6
72	Assessment of porous media combustion with foam porous media for surface/submerged flame. Materials Today: Proceedings, 2018, 5, 20865-20873.	1.8	9

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73	Numerical Investigation on the Effect of Squeegee Angle during Stencil Printing Process. Journal of Physics: Conference Series, 2018, 1082, 012057.	0.4	1
74	High-Speed Fractal Image Compression Featuring Deep Data Pipelining Strategy. IEEE Access, 2018, 6, 71389-71403.	4.2	8
75	Fluid/structure interaction study on the variation of radial gate's gap height in dam. IOP Conference Series: Materials Science and Engineering, 2018, 370, 012063.	0.6	11
76	Synthetic jet cooling diaphragm equation of motion characteristic and verification for computational fluid dynamic modelling. AIP Conference Proceedings, 2018, , .	0.4	1
77	Discrete Phase Model (DPM) study of nano-reinforced Lead Free Solder Sn-3.0Ag-0.5Cu (SAC305). IOP Conference Series: Materials Science and Engineering, 2018, 370, 012067.	0.6	1
78	Synthetic Jet Study on Resonance Driving Frequency for Electronic Cooling. , 2018, , 435-443.		0
79	A practical approach in porous medium combustion for domestic application: A review. IOP Conference Series: Materials Science and Engineering, 2018, 370, 012004.	0.6	8
80	Experiential study on temperature and emission performance of micro burner during porous media combustion. IOP Conference Series: Materials Science and Engineering, 2018, 370, 012057.	0.6	2
81	Characterization and Evaluation of PIV Illumination System Using High Power Light Emitting Diodes for WaterTank Applications. Instruments and Experimental Techniques, 2018, 61, 436-444.	0.5	0
82	EXPERIMENTAL INVESTIGATION ON THE HEAT TRANSFER PERFORMANCE OF HEAT PIPES IN COOLING HEV LITHIUM-ION BATTERIES. Heat Transfer Research, 2018, 49, 1745-1760.	1.6	4
83	EFFECT OF INCLINED ANGLE OF PIN ARRAYS ON FLOW AND HEAT TRANSFER CHARACTERISTICS IN FLOW CHANNEL. , 2018, , .		3
84	Optimization of operating conditions of heat pipes BTMS using response surface method. AIP Conference Proceedings, 2018, , .	0.4	0
85	Pengawalan Pertumbuhan Sebastian antara Logam Sambungan Pateri-Papan Litar Bercetak Menggunakan Salutan Nikel. Sains Malaysiana, 2018, 47, 2157-2162.	0.5	3
86	Effects of the preheat layer thickness on surface/submerged flame during porous media combustion of micro burner. Energy, 2017, 122, 103-110.	8.8	50
87	Assessment of porous media burner for surface/submerged flame during porous media combustion. AIP Conference Proceedings, 2017, , .	0.4	5
88	Heat transfer enhancement by flexible printed circuit board's deformation. International Communications in Heat and Mass Transfer, 2017, 84, 86-93.	5.6	7
89	Study on the Fluid-Structure Interaction at Different Layout of Stacked Chip in Molded Packaging. Arabian Journal for Science and Engineering, 2017, 42, 4743-4757.	3.0	4
90	Heat Transfer in a Loop Heat Pipe Using Fe ₂ NiO ₄ -H ₂ O Nanofluid. MATEC Web of Conferences, 2017, 109, 05001.	0.2	3

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91	Numerical simulation of fluid-structure interaction on flexible PCB with multiple ball grid array components. AIP Conference Proceedings, 2017, , .	0.4	2
92	Discrete phase method study of ball grid array underfill process using nano-silica filler-reinforced composite-encapsulant with varying filler loadings. Microelectronics Reliability, 2017, 72, 45-64.	1.7	25
93	The Effect of Freestream Flow Velocities on the Flexible Printed Circuit Board with Different BGA Package Arrangements. Arabian Journal for Science and Engineering, 2017, 42, 2075-2086.	3.0	4
94	A review of combustion-driven thermoelectric (TE) and thermophotovoltaic (TPV) power systems. Renewable and Sustainable Energy Reviews, 2017, 71, 572-584.	16.4	66
95	Heat transfer enhancement of LEDs with a combination of piezoelectric fans and a heat sink. Microelectronics Reliability, 2017, 68, 39-50.	1.7	31
96	Numerical simulation of self-alignment of chip resistor components for different silver content during reflow soldering. Microelectronics Reliability, 2017, 79, 69-78.	1.7	27
97	Experiment on forced convective heat transfer enhancement using MWCNTs/GNPs hybrid nanofluid and mini-tube. International Journal of Heat and Mass Transfer, 2017, 115, 1121-1131.	4.8	75
98	Influence of Material Properties on the Fluid-Structure Interaction aspects during Molded Underfill Process. MATEC Web of Conferences, 2017, 97, 01059.	0.2	8
99	Experimental and numerical investigation of flow and thermal effects on flexible printed circuit board. Microelectronics Reliability, 2017, 72, 5-17.	1.7	10
100	Discrete phase method particle simulation of ultra-fine package assembly with SAC305-TiO 2 nano-reinforced lead free solder at different weighted percentages. Microelectronics Reliability, 2017, 79, 336-351.	1.7	9
101	Molded underfill (MUF) encapsulation for flip-chip package: A numerical investigation. AIP Conference Proceedings, 2017, , .	0.4	3
102	CUF scaling effect on contact angle and threshold pressure. Soldering and Surface Mount Technology, 2017, 29, 173-190.	1.5	15
103	A study on thermoforming process of stretchable circuit and its performance in manufacturing of automotive lighting. AIP Conference Proceedings, 2017, , .	0.4	4
104	Comparative Study of the Scaling Effect on Pressure Profiles in Capillary Underfill Process. IOP Conference Series: Materials Science and Engineering, 2017, 203, 012012.	0.6	2
105	Scaling Effect on Velocity Profiles in Capillary Underfill Flow. IOP Conference Series: Materials Science and Engineering, 2017, 203, 012013.	0.6	1
106	Influence of low concentration of diamond water nanofluid in loop heat pipe. International Journal of Heat and Technology, 2017, 35, 539-548.	0.6	5
107	Effects of Aspect Ratio in Moulded Packaging Considering Fluid/Structure Interaction: A CFD Modelling Approach. Journal of Applied Fluid Mechanics, 2017, 10, 1799-1811.	0.2	5
108	LIFE CYCLE ASSESSMENT OF TOXICITY POTENTIAL OF METALLIC ELEMENTS AND PROCESS STAGES IN ELECTRONICS: A CASE STUDY OF ELECTRONIC CONNECTOR LEADS. Environmental Engineering and Management Journal, 2017, 16, 1521-1530.	0.6	0

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109	Unsteady Pressure Distribution of a Flapping Wing Undergoing Root Flapping Motion with Elbow Joint at Different Reduced Frequencies. International Review of Aerospace Engineering, 2017, 10, 105.	0.3	0
110	APPLYING NUMERICAL METHOD IN IMPROVING EMERGENCY GATE DESIGN OF MENGKUANG DAM. Advances and Applications in Fluid Mechanics, 2017, 20, 353-362.	0.1	0
111	Influence of printed circuit board thickness in wave soldering. Scientia Iranica, 2017, .	0.4	6
112	Compact Multislot Planar Monopole Antenna for Microwave Imaging. Advanced Science Letters, 2017, 23, 11031-11034.	0.2	0
113	Lattice Boltzmann Model of 3D Multiphase Flow in Artery Bifurcation Aneurysm Problem. Computational and Mathematical Methods in Medicine, 2016, 2016, 1-17.	1.3	8
114	Detection of Cracks in Concrete Structure Using Microwave Imaging Technique. International Journal of Microwave Science and Technology, 2016, 2016, 1-6.	0.6	7
115	Improvement of Porous Porcelain through Glaze Coating. Materials Science Forum, 2016, 840, 19-23.	0.3	0
116	Effect of thermocapillary action in the underfill encapsulation of multi-stack ball grid array. Microelectronics Reliability, 2016, 66, 143-160.	1.7	22
117	Comparative assessment of a porous burner using vegetable cooking oil–kerosene fuel blends for thermoelectric and thermophotovoltaic power generation. Fuel, 2016, 180, 137-147.	6.4	14
118	High-speed implementation of fractal image compression in low cost FPGA. Microprocessors and Microsystems, 2016, 47, 429-440.	2.8	13
119	Effect of ILU dispensing types for different solder bump arrangements on CUF encapsulation process. Microelectronic Engineering, 2016, 163, 83-97.	2.4	26
120	Lattice Boltzmann method study of effect three dimensional stacking-chip package layout on micro-void formation during encapsulation process. Microelectronics Reliability, 2016, 65, 205-216.	1.7	15
121	Real-time implementation of Fractal Image Compression in low cost FPGA. , 2016, , .		4
122	FVM based simulation on multi-stack ball grid array (BGA). AIP Conference Proceedings, 2016, , .	0.4	0
123	Hardness profiles of Sn-3.0Ag-0.5Cu-TiO ₂ composite solder by nanoindentation. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2016, 669, 178-186.	5.6	28
124	Backward Compatibility Solder Joint Formation at High Peak Reflow Temperature for Aerospace Applications. Arabian Journal for Science and Engineering, 2016, 41, 1813-1823.	1.1	4
125	Effect of Wing Deformation on the Aerodynamic Performance of Flapping Wings: Fluid-Structure Interaction Approach. Journal of Aerospace Engineering, 2016, 29, .	1.4	13
126	Microstructure and mechanical properties of Pb-free Sn–3.0Ag–0.5Cu solder pastes added with NiO nanoparticles after reflow soldering process. Materials and Design, 2016, 90, 499-507.	7.0	65

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127	Finite volume-based simulation of the wave soldering process: Influence of the conveyor angle on pin-through-hole capillary flow. Numerical Heat Transfer; Part A: Applications, 2016, 69, 295-310.	2.1	13
128	Lattice Boltzmann method study of bga bump arrangements on void formation. Microelectronics Reliability, 2016, 56, 170-181.	1.7	29
129	Numerical Investigation on the Effect of Pressure and Temperature on the Melt Filling During Injection Molding Process. Arabian Journal for Science and Engineering, 2016, 41, 1907-1919.	1.1	10
130	Thermo-mechanical challenges of reflowed lead-free solder joints in surface mount components: a review. Soldering and Surface Mount Technology, 2016, 28, 41-62.	1.5	47
131	Physical, mechanical, and thermal properties improvement of porous alumina substrate through dip-coating and re-sintering procedures. Ceramics International, 2016, 42, 7717-7729.	4.8	10
132	Single-phase heat transfer enhancement in micro/minichannels using nanofluids: Theory and applications. Applied Energy, 2016, 164, 733-755.	10.1	125
133	Effect of ceramic coating in combustion and cogeneration performance of Al ₂ O ₃ porous medium. Journal of the Energy Institute, 2016, 89, 81-93.	5.3	21
134	Lattice Boltzmann Method of Different BGA Orientations on I-Type Dispensing Method. PLoS ONE, 2016, 11, e0159357.	2.5	14
135	Effects of Temperature on the Wave Soldering of Printed Circuit Boards: CFD Modeling Approach. Journal of Applied Fluid Mechanics, 2016, 9, 2053-2062.	0.2	6
136	Thermal fluid-structure interaction of PCB configurations during the wave soldering process. Soldering and Surface Mount Technology, 2015, 27, 31-44.	1.5	12
137	Piezoresistive effects in controllable defective HfTCVD graphene-based flexible pressure sensor. Scientific Reports, 2015, 5, 14751.	3.3	53
138	A computational fluid dynamics analysis of the wave soldering process. International Journal of Numerical Methods for Heat and Fluid Flow, 2015, 25, 1231-1247.	2.8	3
139	Oxygen Uptake by Biological Processes inside Oxidation Ditch. Applied Mechanics and Materials, 2015, 802, 490-495.	0.2	0
140	Experimental analysis and FEM simulation of loop heat charged with diamond nanofluid for desktop PC cooling. IOP Conference Series: Materials Science and Engineering, 2015, 88, 012038.	0.6	3
141	Combustion Characteristics of Butane Porous Burner for Thermoelectric Power Generation. Journal of Combustion, 2015, 2015, 1-13.	1.0	5
142	Characteristic Airflow Patterns During Inspiration and Expiration: Experimental and Numerical Investigation. Journal of Medical and Biological Engineering, 2015, 35, 387-394.	1.8	11
143	Optimization of SiO ₂ nanoparticle mass concentration and heat input on a loop heat pipe. Case Studies in Thermal Engineering, 2015, 6, 238-250.	5.7	21
144	Numerical investigations on the effects of different cooling periods in reflow-soldering process. Heat and Mass Transfer, 2015, 51, 1413-1423.	2.1	17

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145	Effects of diamond nanoparticles reinforcement into lead-free Sn-3.0Ag-0.5Cu solder pastes on microstructure and mechanical properties after reflow soldering process. <i>Materials and Design</i> , 2015, 82, 206-215.	7.0	54
146	Optimization of pin through hole connector in thermal fluid-structure interaction analysis of wave soldering process using response surface methodology. <i>Simulation Modelling Practice and Theory</i> , 2015, 57, 45-57.	3.8	16
147	Experimental analysis of a porous burner operating on kerosene-vegetable cooking oil blends for thermophotovoltaic power generation. <i>Energy Conversion and Management</i> , 2015, 96, 544-560.	9.2	18
148	Experimental and numerical investigation of 3D gas flow temperature field in infrared heating reflow oven with circulating fan. <i>International Journal of Heat and Mass Transfer</i> , 2015, 87, 49-58.	4.8	43
149	Reflow Optimization Process: Thermal Stress Using Numerical Analysis and Intermetallic Spallation in Backwards Compatibility Solder Joints. <i>Arabian Journal for Science and Engineering</i> , 2015, 40, 1669-1679.	1.1	9
150	Effect of Skin Flexibility on Aerodynamic Performance of Flexible Skin Flapping Wings for Micro Air Vehicles. <i>Experimental Techniques</i> , 2015, 39, 11-20.	1.5	9
151	Centrifuge and storage precipitation of TiO ₂ nanoparticles by the sol-gel method. <i>Journal of Alloys and Compounds</i> , 2015, 651, 557-564.	5.5	20
152	Effects of PCB thickness on adjustable fountain wave soldering. <i>Sadhana - Academy Proceedings in Engineering Sciences</i> , 2015, 40, 2197-2220.	1.3	5
153	Effects of Fe ₂ NiO ₄ nanoparticles addition into lead free Sn-3.0Ag-0.5Cu solder pastes on microstructure and mechanical properties after reflow soldering process. <i>Materials & Design</i> , 2015, 67, 197-208.	5.1	51
154	Experimental investigation of the performance of a liquid fuel-fired porous burner operating on kerosene-vegetable cooking oil (VCO) blends for micro-cogeneration of thermoelectric power. <i>Renewable Energy</i> , 2015, 74, 505-516.	8.9	17
155	LIFT PERFORMANCE OF A CAMBERED WING FOR AERODYNAMIC PERFORMANCE ENHANCEMENT OF THE FLAPPING WING. <i>Jurnal Teknologi (Sciences and Engineering)</i> , 2015, 75, .	0.4	0
156	Effects of Solder Temperature on Pin Through-Hole during Wave Soldering: Thermal-Fluid Structure Interaction Analysis. <i>Scientific World Journal</i> , The, 2014, 2014, 1-13.	2.1	6
157	The Effect of Morphing Force on Aerodynamic Performances of TM Wing. <i>Advanced Materials Research</i> , 2014, 980, 102-106.	0.3	0
158	Analytical Comparisons of Standardized Nasal Cavity. <i>Journal of Medical Imaging and Health Informatics</i> , 2014, 4, 14-20.	0.3	5
159	Applications of Porous Media Combustion Technology. , 2014, , 615-633.		9
160	Experimental Study on the Effect of Skin Flexibility on Aerodynamic Performance of Flapping Wings for Micro Air Vehicles. <i>Applied Mechanics and Materials</i> , 2014, 629, 18-23.	0.2	2
161	Effect of piezoelectric fan mode shape on the heat transfer characteristics. <i>International Communications in Heat and Mass Transfer</i> , 2014, 52, 140-151.	5.6	36
162	Implications of Adjustable Fountain Wave in Pin Through Hole Soldering Process. <i>Arabian Journal for Science and Engineering</i> , 2014, 39, 9101-9111.	1.1	5

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163	Thermal Performance of a Cylindrical Heat Pipe for Different Heat Inputs and Inclination Angles. Applied Mechanics and Materials, 2014, 661, 148-153.	0.2	6
164	Fluid-structure interaction analysis on the effect of chip stacking in a 3D integrated circuit package with through-silicon vias during plastic encapsulation. Microelectronic Engineering, 2014, 113, 40-49.	2.4	35
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166	CFD modeling of pin shape effects on capillary flow during wave soldering. International Journal of Heat and Mass Transfer, 2014, 72, 400-410.	4.8	44
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